



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31C680KBCNBND

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 68pF, 50V, ±10%, C0G, 1206

## A. Samsung Part Number

<u>CL</u> <u>31</u> <u>C</u> <u>680</u> <u>K</u> <u>B</u> <u>C</u> <u>N</u> <u>B</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1 Series      | Samsung Multi-layer Cera | Samsung Multi-layer Ceramic Capacitor |                                  |  |
|---------------|--------------------------|---------------------------------------|----------------------------------|--|
| ② Size        | 1206 (inch code)         | L: 3.2 ± 0.15 mm                      | W: 1.6 ± 0.15 mm                 |  |
|               |                          |                                       |                                  |  |
| 3 Dielectric  | C0G                      | 8 Inner electrode                     | Ni                               |  |
| 4 Capacitanc  | <b>e</b> 68 pF           | Termination                           | Cu                               |  |
| ⑤ Capacitanc  | e ±10 %                  | Plating                               | Sn 100% (Pb Free)                |  |
| tolerance     |                          | Product                               | Array(4-element)                 |  |
| 6 Rated Volta | ige 50 V                 | Special                               | Reserved for future use          |  |
| 7 Thickness   | 0.85 ± 0.15 mm           | ① Packaging                           | Cardboard Type,13"reel(10,000ea) |  |

## **B. Samsung Reliability Test and Judgement condition**

|                   | Performance   | Test condition                        |  |
|-------------------|---|---------------------------------------|--|
| Capacitance       | Within specified tolerance  | 1tht±10% 0.5~5Vrms                    |  |
| Q                 | 1000 min  | 1                                     |  |
| Insulation        | More than 500Mohm⋅μF  | Rated Voltage 60~120 sec.             |  |
| Resistance        |   |                                       |  |
| Appearance        | No abnormal exterior appearance                                   | Visual inspection                     |  |
| Withstanding      | No dielectric breakdown or  | 300% of the rated voltage             |  |
| Voltage           | mechanical breakdown  |                                       |  |
| Temperature       | COG   |                                       |  |
| Characteristics   | (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) |                                       |  |
| Adhesive Strength | No peeling shall be occur on the                                  | 500g·F, for 10±1 sec.                 |  |
| of Termination    | terminal electrode  |                                       |  |
| Bending Strength  | Capacitance change: within ±5%                                    | Bending to the limit (1mm)            |  |
|                   |   | with 1.0mm/sec.                       |  |
| Solderability     | More than 75% of terminal surface                                 | SnAg3.0Cu0.5 solder                   |  |
|                   | is to be soldered newly   | 245±5℃, 3±0.3sec.                     |  |
|                   |   | (preheating : 80~120 ℃ for 10~30sec.) |  |
|                   |   |                                       |  |
| Resistance to     | Capacitance change: within ±2.5%                                  | Solder pot : 270±5℃, 10±1sec.         |  |
| Soldering heat    | Tan δ, IR : initial spec.   |                                       |  |
|                   |   |                                       |  |

|                  | Performance                      | Test condition   |
|------------------|----------------------------------|--|
| Vibration Test   | Capacitance change: within ±2.5% | Amplitude: 1.5mm   |
|                  | Tan δ, IR : initial spec.        | From 10Hz to 55Hz (return : 1min.)                       |
|                  |                                  | 2hours × 3 direction (x, y, z)                           |
| Moisture         | Capacitance change: within ±7.5% | With rated voltage                                       |
| Resistance       | Q: 200 min                       | 40±2℃, 90~95%RH, 500 +12/-0 hour                         |
|                  | IR : More than 25MΩ·μF           |  |
| High Temperature | Capacitance change: within ±3%   | With 200% of the rated voltage                           |
| Resistance       | Q: 350 min                       | Max. operating temperature                               |
|                  | IR : More than 50MΩ·μF           | 1000+48/-0 hour  |
| Temperature      | Capacitance change: within ±2.5% | 1 cycle condition  |
| Cycling          | Tan δ, IR : initial spec.        | Min. operating temperature $\rightarrow$ 25 $^{\circ}$ C |
|                  |                                  | → Max. operating temperature → 25°C                      |
|                  |                                  | 5 cycles test  |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.